

Free Forum: Reliability Summit

“Keeping industry reliability test protocols current with rapidly changing markets”

Friday February 23, 2007. 8:30-4:30
 Room 404AB Los Angeles Convention Center
 1201 S. Figueroa St. Los Angeles, California

Agenda

Time	Topic	Speaker
8:30	Welcome and purpose of summit	David Bergman, IPC
8:40	Roadmap person to set the stage	Jack Fisher, IPC -
Association activities		
9:00	IPC Reliability activities	Reza Ghaffarian
9 :30	iNEMI activities	Bob Pfahl
10 :00	Break	
10:30	HDPUG activities	Marshall Andrews
11:00	GEIA activities	Lloyd Condra, Boeing
11:15	IEC activities	Dieter Bergman
11:30	JPCA activities	Aki Shibata
12:00	Lunch on own	
University activities		
1:00	SUNY Binghamton	Michael DiPietro
1:30	CALCE	Michael Osterman
OEM activities		
2:00	JGPP/JCAA (NASA-DOD)	Dave Hillman Rockwell/Tom Woodrow, Boeing
2:30	Sun Microsystems	Mike Freda, Karl Sauter
3:00	Correlation of Material properties to their Reliability	Vasu Vasudevan, Intel

	performance of High Density BGA Package solder joints.	
3:30	Brainstorming GAPS Standards needs Action plan	All
4:30	Adjourn	